

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10050013	FILING DATE 01/17/2002	CLASS 427	SUBCLASS 1	GAU 1762	EXAMINER <i>J. C. G.</i>
**APPLICANTS: Khaselev Oscar; Zavarine Igor; Zhang Yun;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO <i>Khaselev 1-1-7</i>	
Verified and Acknowledged Examiner's initials					
TITLE : Electroplating solution for high speed plating of tin-copper solder					
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.		Figs.Drwg.
		Print Fig.		
TERMINAL DISCLAIMER		Primary Examiner		
		Application Examiner		
PREPARED FOR ISSUE				
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